

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/16/2022

Details for "74ALVCH16373DGGRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
74ALVCH16373DGGRG4	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DGG 48	6.1x12.5x1.15	278.6

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.340004	99.997647	999976	0.122057	1221
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000294	3	0	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000294	3	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000001	0.000294	3	0	0
Precious Metals	Silver	7440-22-4	0.000005	0.001471	15	0.000002	0
Sub-Total			0.340012	100	1000000	0.12206	1221
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.829134	80.000039	800000	0.297648	2976
Thermoplastics	Epoxy	85954-11-6	0.207283	19.999961	200000	0.074412	744
Sub-Total			1.036417	100	1000000	0.37206	3721
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	115.351325	97.526484	975265	41.409564	414096
Copper and Its Alloys	Iron	7439-89-6	2.718738	2.298621	22986	0.97599	9760
Copper and Its Alloys	Phosphorus	7723-14-0	0.017731	0.014991	150	0.006365	64
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.035462	0.029982	300	0.01273	127
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.035462	0.029982	300	0.01273	127
Zinc and Its Alloys	Zinc	7440-66-6	0.118206	0.09994	999	0.042434	424
Sub-Total			118.276924	100	1000000	42.459814	424598
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.14144	95.12	951200	0.409762	4098
Precious Metals	Gold	7440-57-5	0.00936	0.78	7800	0.00336	34
Precious Metals	Palladium	7440-05-3	0.0492	4.1	41000	0.017662	177
Sub-Total			1.2	100	1000000	0.430784	4308
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	132.71231	86	860000	47.641922	476419
Other Plastics and Rubber	Carbon Black	1333-86-4	0.46295	0.3	3000	0.166193	1662
Thermoplastics	Epoxy	85954-11-6	21.14138	13.7	137000	7.589469	75895
Sub-Total			154.31664	100	1000000	55.397584	553976
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.392046	100	1000000	1.217699	12177
Sub-Total			3.392046	100	1000000	1.217699	12177
Total			278.562039			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.